

The Revoltec Thermal Grease Diamond uses diamond dust to provide effective cooling of CPUs, VGA processors and chipsets.



Technical Data:

Type	Non-curing compound
Capacity	6 g
Specific Gravity (g/cm ³):	~ 2.4
Thermal Conductivity (W/m °K)	4
Thermal Resistance (°C/W)	0,087
Electrical Conductivity	No
Temperature range	-50°C - +240°C

integrated brush

The integrated brush in the screw cap facilitates an very easy and smooth application of the heat-conducting paste.

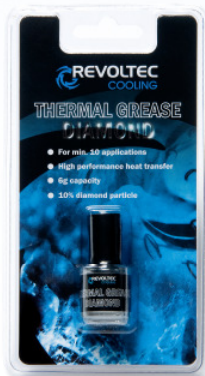


quick heat transfer

The Revoltec Thermal Grease Diamond heat-conducting paste is comprised of 10% diamond dust to facilitate quick heat transfer, providing even more efficient cooling.

up to at least 10 applications

The Revoltec Thermal Grease Diamond heat-conducting paste is delivered in a glass vial containing 6g of the compound, enough for at least 10 applications.



Retail Packaging

Logistic Data

Weight:	packaging unit:	package size:	manufacturer number:	EAN-Code
Net: 6g	100 pcs./p.u.	178 x 94 x 30 mm (LxWxH)	RZ034	4260048814465
Gross: 30g	460 x 375 x 330 (LxWxH)			